

ABSTRACT OF THE DISCLOSURE

There is disclosed a method of forming stress-adjusted insulating films which are interposed between respective interconnection layers upon laminating metal interconnection layers in excess of three-layer.

- 5 Multiple layers whose total stress is adjusted are formed by laminating insulating films 22a to 22e, 23a to 23d on a substrate 21.

0897839-072197
/6T2/0"6E8/6880